



# 100% Material Declaration Data Sheet BG225

PK143 (v1.2.1) January 8, 2007

Material Declaration Data Sheet

**Average Weight: 2.599 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.0735</b>	<b>2.83%</b>
	Silicon	7440-21-3	100.00		0.0735	
<b>Die Attach Material</b>					<b>0.0073</b>	<b>0.28%</b>
	Resin	Trade Secret	22.00		0.0016	
	Silver	7440-22-4	78.00		0.0057	
<b>Mold Compound</b>					<b>1.0846</b>	<b>41.73%</b>
	Resin	Trade Secret	12.00		0.1302	
	Silica	60676-86-0	88.00	Filler	0.9544	
<b>Laminate</b>					<b>1.1403</b>	<b>43.87%</b>
	Laminate	Trade Secret		Metal Layer	0.5613	
	Solder Mask (EP)	Trade Secret			0.0878	
	Copper	7440-50-8		Metal Layer	0.4662	
	Nickel	7440-02-0		Metal Layer	0.0209	
	Gold	7440-57-5		Metal Layer	0.0041	
<b>Gold Wire</b>					<b>0.0117</b>	<b>0.45%</b>
	Gold	7440-57-5	100.00		0.0118	
<b>Solder Balls</b>					<b>0.2816</b>	<b>10.83%</b>
	Tin	7440-31-5	63.00		0.1774	
	Lead	7439-92-1	37.00		0.1042	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/23/06	1.0	Initial release.
7/12/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
1/8/07	1.2.1	Corrected Gold Wire CAS# entry.